

REMARKS

Amendments to the Specification

The "Cross Reference To Related Applications" has been amended to add a patent number for the issued parent application. In addition, the "Cross Reference To Related Applications" has been amended to cite four related applications, which are divisions of the parent application.

In addition, page 11, line 11, of the specification has been amended correct an informality. In particular, "Figure 6" has been changed to "Figure 7".

Further, an informality has been corrected on page 60 (i.e., contact bumps 24PGA on line 17 should be contact bumps 24A).

Claim Objections

Claim 91 has been objected to as including inconsistent recitations relative to claim 76. In response to this objection, claim 91 has been amended to be similar to claim 76 (i.e., terminal contacts in electrical communication with the die contacts).

Allowed And Objected To Claims

Claims 76-89 and 97-113 have been allowed.

Claim 91 has been objected to as being dependent on a rejected base claim but would be allowable if rewritten in independent form. In response to this objection, claim 91 has been rewritten in independent form with the limitations of claim 90. In addition, claims 92-96 have been amended to depend on claim 91, and to include limitations that are consistent with amended claim 91.

Rejections Under 35 USC §102

Claims 90 and 91-96 have been rejected under 35 USC §102(b) as being anticipated by Kuisl et al. (US Patent No. 6,020,217).

As stated above, claim 91 has been rewritten in independent form, and claims 92-96 have been amended to depend on claim 91. This leaves only claim 90 subject to the rejection under 35 USC §102 over Kuisl et al.

In response to this rejection, claim 90 has been amended to recite the step of "forming a plurality of contact bumps on the die contacts configured to provide contacts for stacking or testing". The contact bumps 24PGA are shown in Figures 19B-19G. In addition, the forming step for the contact bumps is described on page 60, lines 13-17 of the specification. Further, the specification states on page 40, lines 1-3 in describing equivalent contact bumps 24A: "the contact bumps 24A can be used to stack multiple components and to provide contact points for testing the components 16A".

In Kuisl et al. an encapsulating compound 4 (Figure 1B) and a silicon cover 5 (Figure 1B) are formed on the bonding pads 3. Accordingly, the presently claimed forming step for contact bumps is not disclosed or suggested by Kuisl et al.


The additional step is submitted to make amended claim 90 both novel and unobvious over Kuisl et al. One indicia of unobviousness is that an improved component is provided, as it can be more easily stacked and tested.

Conclusion

In view of the amendments and arguments, favorable consideration and allowance of claims 76-113 is requested. Also being submitted with this Amendment is an Information Disclosure Statement. Should any issues arise that will advance this case to allowance, the Examiner is asked to contact the undersigned by telephone.

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